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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	25
Program Memory Size	28KB (16K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 5.5V
Data Converters	A/D 17x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SSOP (0.209", 5.30mm Width)
Supplier Device Package	28-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f1518-e-ss

1.2 Pin Utilization

Five pins are needed for ICSP™ programming. The pins are listed in Table 1-1 and Table 1-2.

TABLE 1-1: PIN DESCRIPTIONS DURING PROGRAMMING – PIC16(L)F1526 AND PIC16(L)F1527

Pin Name	During Programming		
	Function	Pin Type	Pin Description
RB6	ICSPCLK	I	Clock Input – Schmitt Trigger Input
RB7	ICSPDAT	I/O	Data Input/Output – Schmitt Trigger Input
RG5/$\overline{MCLR}$/VPP	Program/Verify mode	P(1)	Program Mode Select/Programming Power Supply
VDD	VDD	P	Power Supply
VSS	VSS	P	Ground

Legend: I = Input, O = Output, P = Power

Note 1: The programming high voltage is internally generated. To activate the Program/Verify mode, high voltage needs to be applied to $\overline{MCLR}$ input. Since the $\overline{MCLR}$ is used for a level source, $\overline{MCLR}$ does not draw any significant current.

TABLE 1-2: PIN DESCRIPTIONS DURING PROGRAMMING – PIC16(L)F1512, PIC16(L)F1513, PIC16(L)F1516, PIC16(L)F1517, PIC16(L)F1518 and PIC16(L)F1519

Pin Name	During Programming		
	Function	Pin Type	Pin Description
RB6	ICSPCLK	I	Clock Input – Schmitt Trigger Input
RB7	ICSPDAT	I/O	Data Input/Output – Schmitt Trigger Input
RE3/$\overline{MCLR}$/VPP	Program/Verify mode	P(1)	Program Mode Select/Programming Power Supply
VDD	VDD	P	Power Supply
VSS	VSS	P	Ground

Legend: I = Input, O = Output, P = Power

Note 1: The programming high voltage is internally generated. To activate the Program/Verify mode, high voltage needs to be applied to $\overline{MCLR}$ input. Since the $\overline{MCLR}$ is used for a level source, $\overline{MCLR}$ does not draw any significant current.

2.0 DEVICE PINOUTS

The pin diagrams for the PIC16(L)F151X/152X family are shown in Figure 2-1 through Figure 2-7. The pins that are required for programming are listed in Table 1-1 and shown in bold lettering in the pin diagrams.

FIGURE 2-1: 28-PIN SPDIP, SOIC, SSOP DIAGRAM FOR PIC16(L)F1512, PIC16(L)F1513, PIC16(L)F1516 AND PIC16(L)F1518

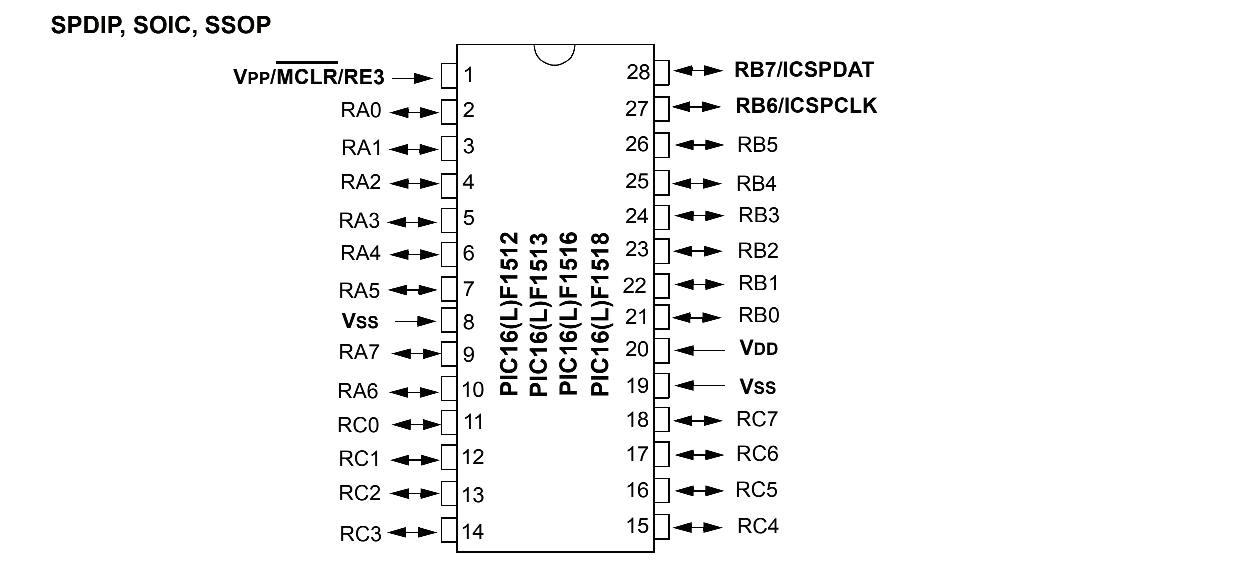

FIGURE 2-3: 40-PIN PDIP DIAGRAM FOR PIC16(L)F1517 AND PIC16(L)F1519

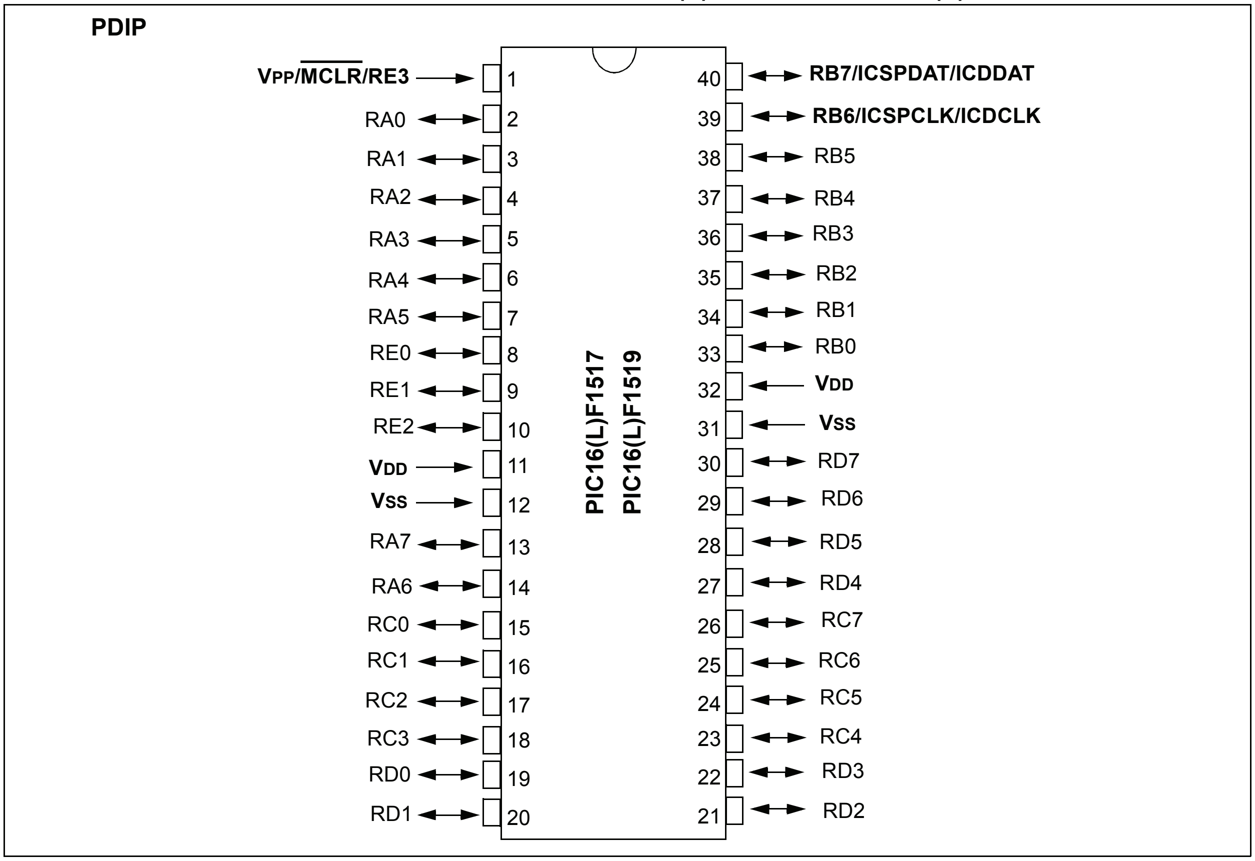

FIGURE 2-4: 40-PIN UQFN DIAGRAM FOR PIC16(L)F1517 AND PIC16(L)F1519

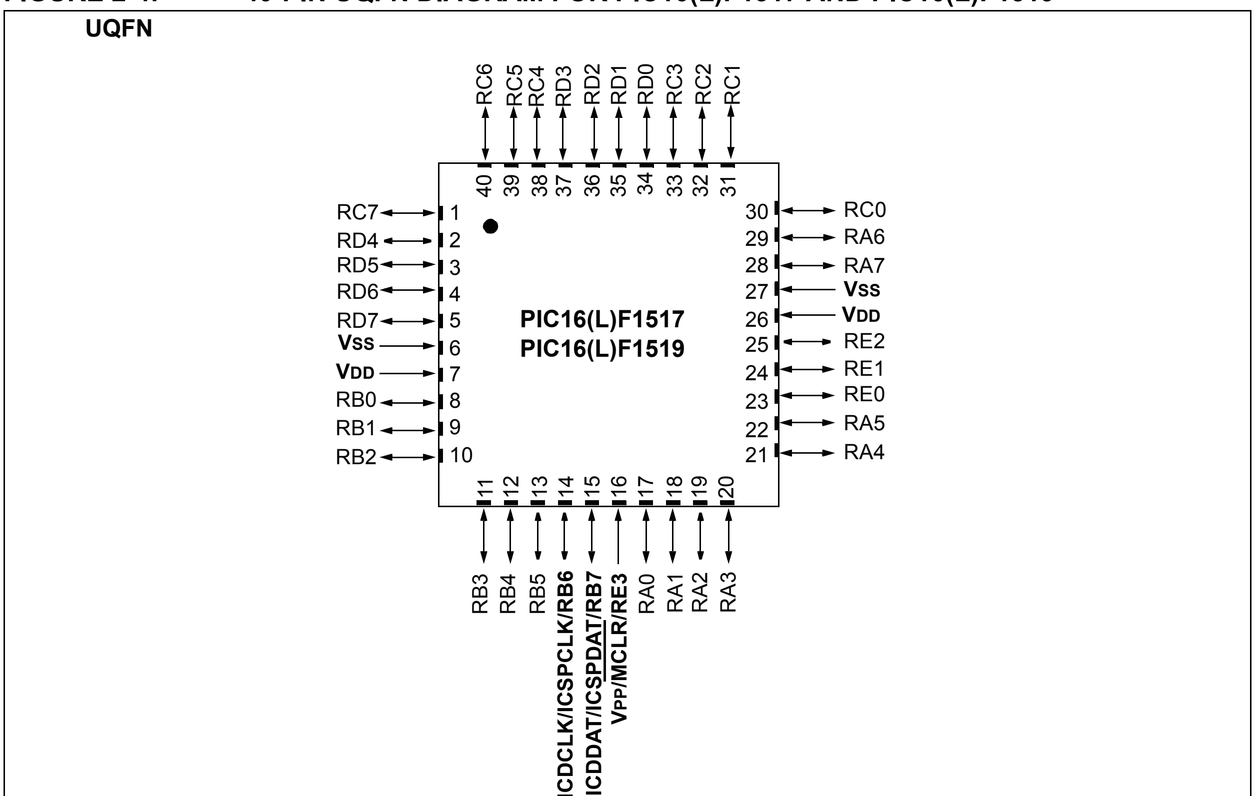

FIGURE 2-5: 44-PIN TQFP DIAGRAM FOR PIC16(L)F1517 AND PIC16(L)F1519

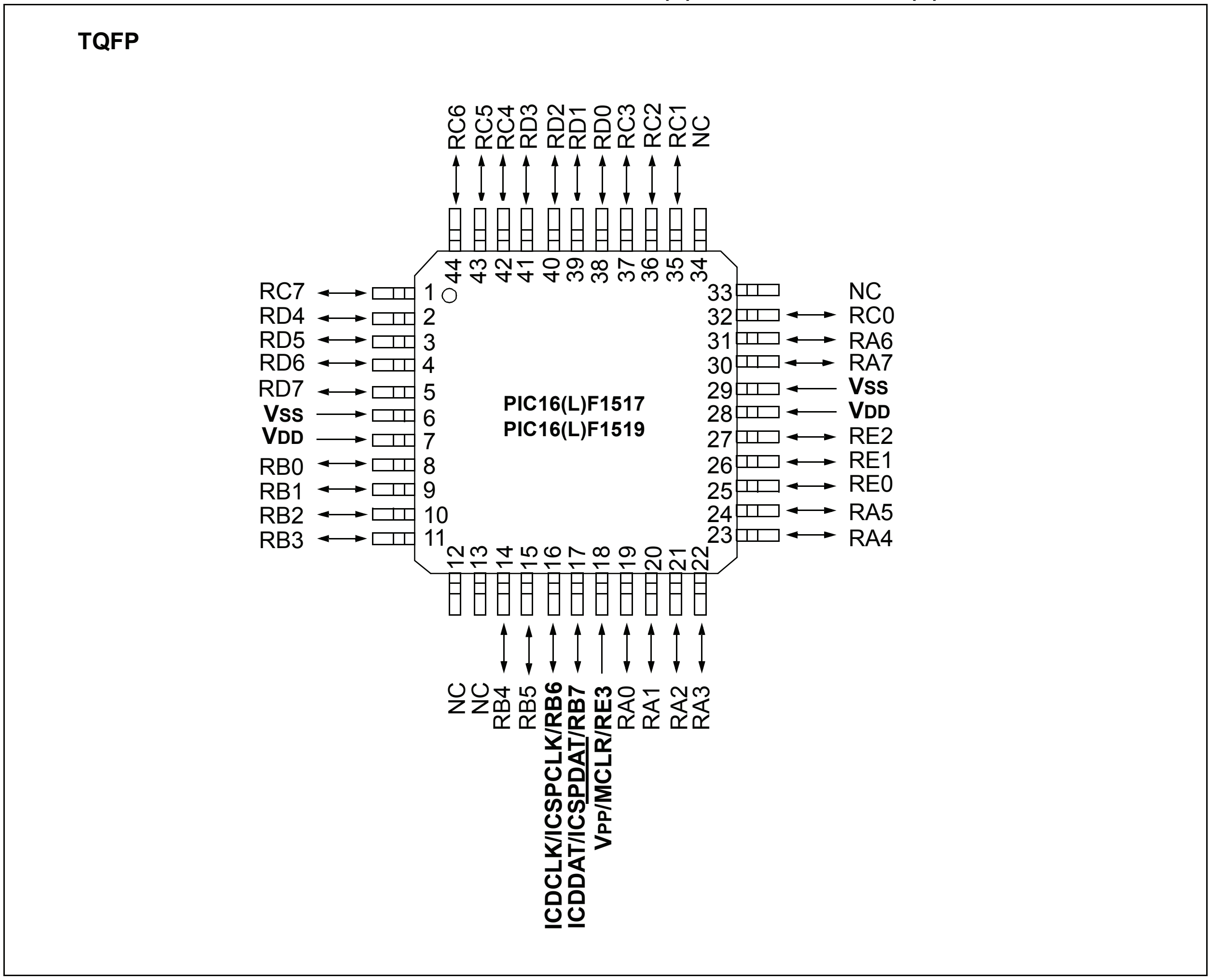

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FIGURE 2-6: 64-PIN QFN DIAGRAM FOR PIC16(L)F1526 AND PIC16(L)F1527

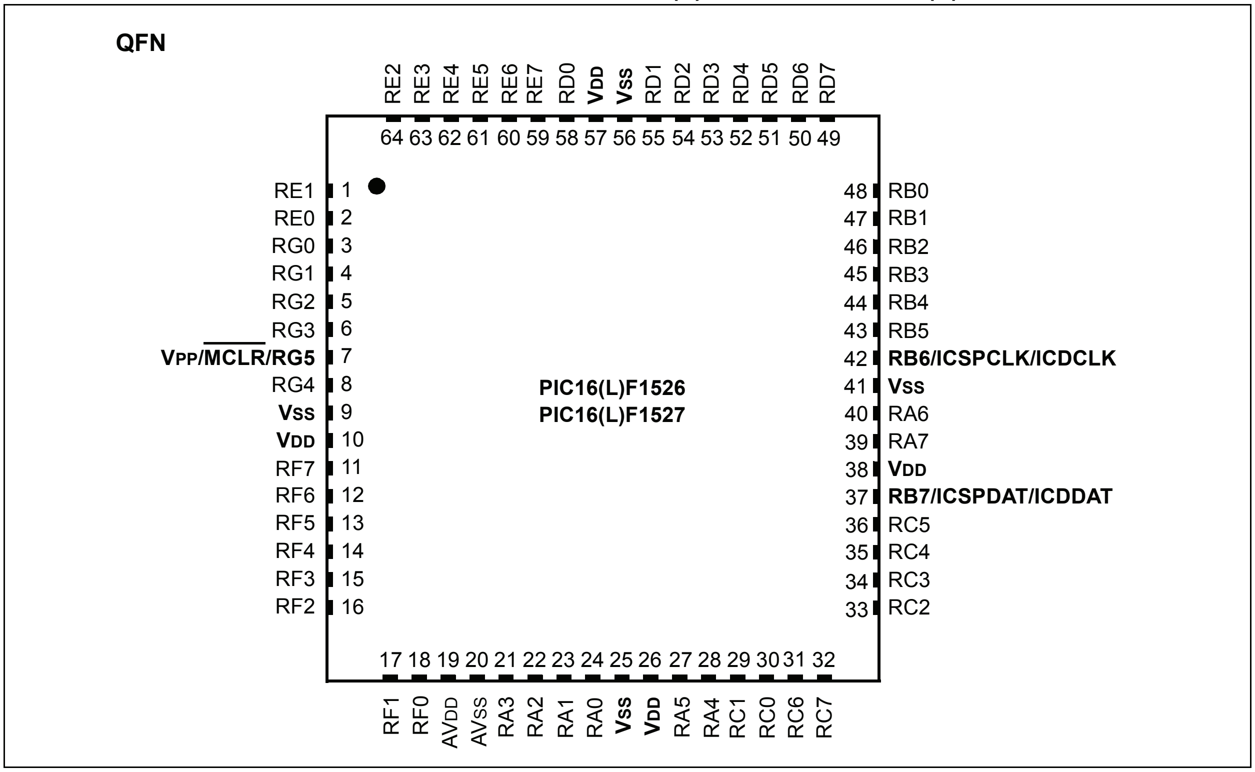
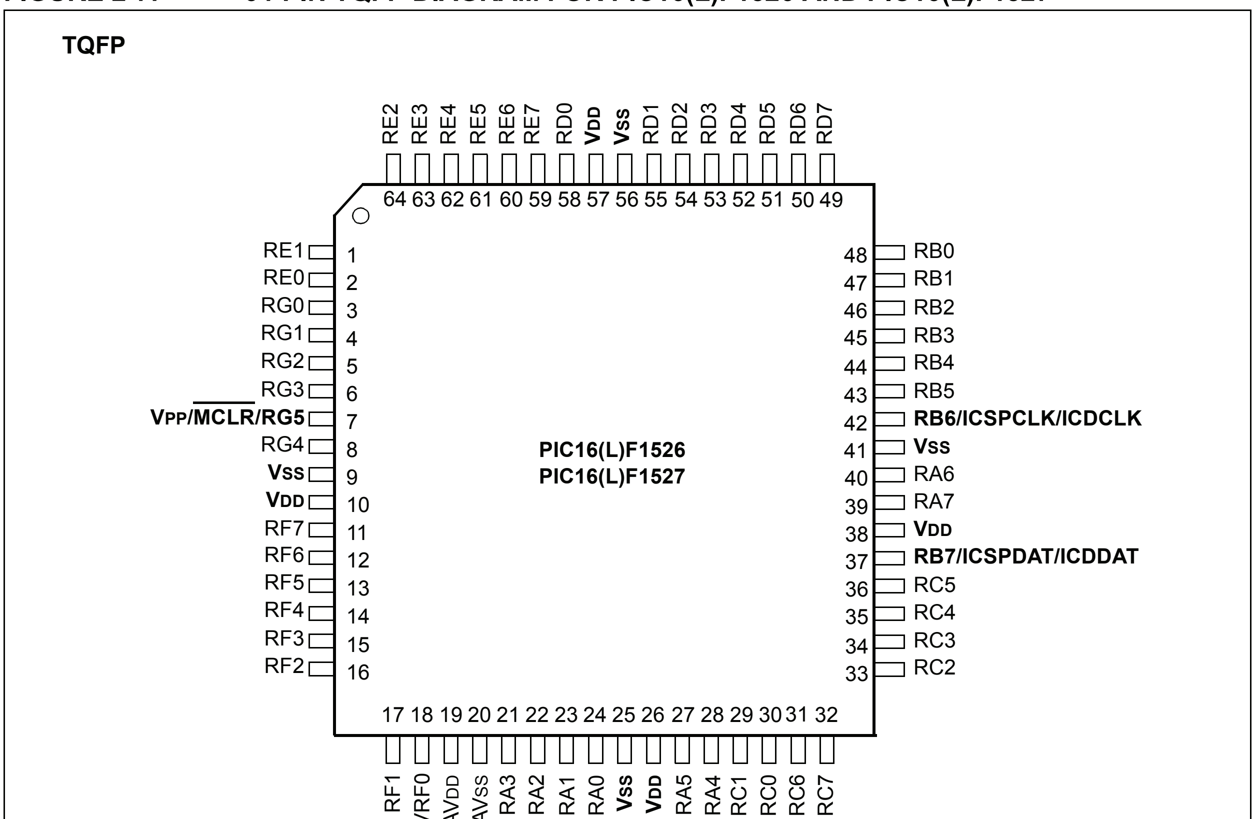


FIGURE 2-7: 64-PIN TQFP DIAGRAM FOR PIC16(L)F1526 AND PIC16(L)F1527



3.0 MEMORY MAP

The memory for the PIC16(L)F151X/152X devices is broken into two sections: program memory and configuration memory. Only the size of the program memory changes between devices, the configuration memory remains the same.

FIGURE 3-1: PIC16(L)F1512 PROGRAM MEMORY MAPPING

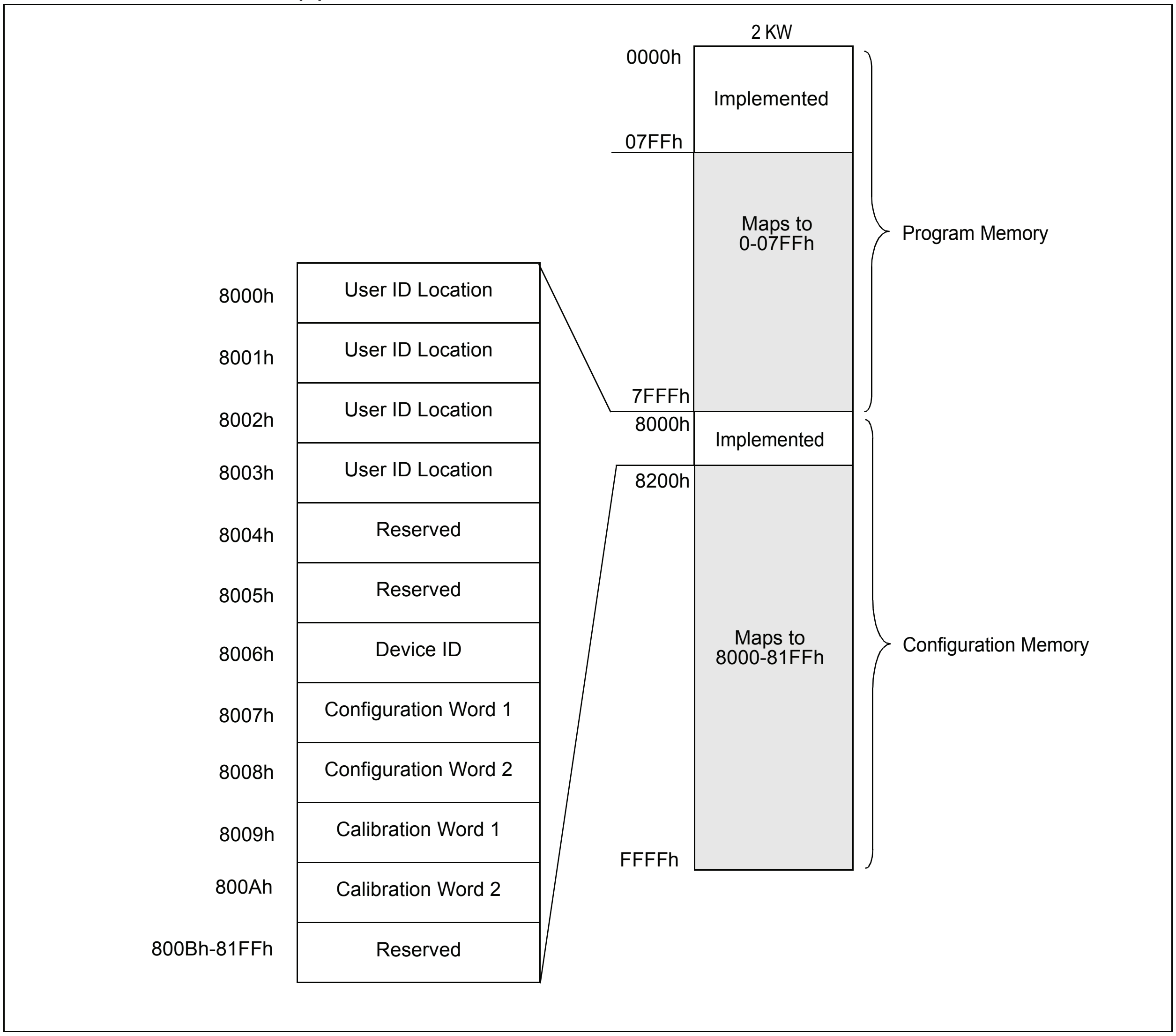


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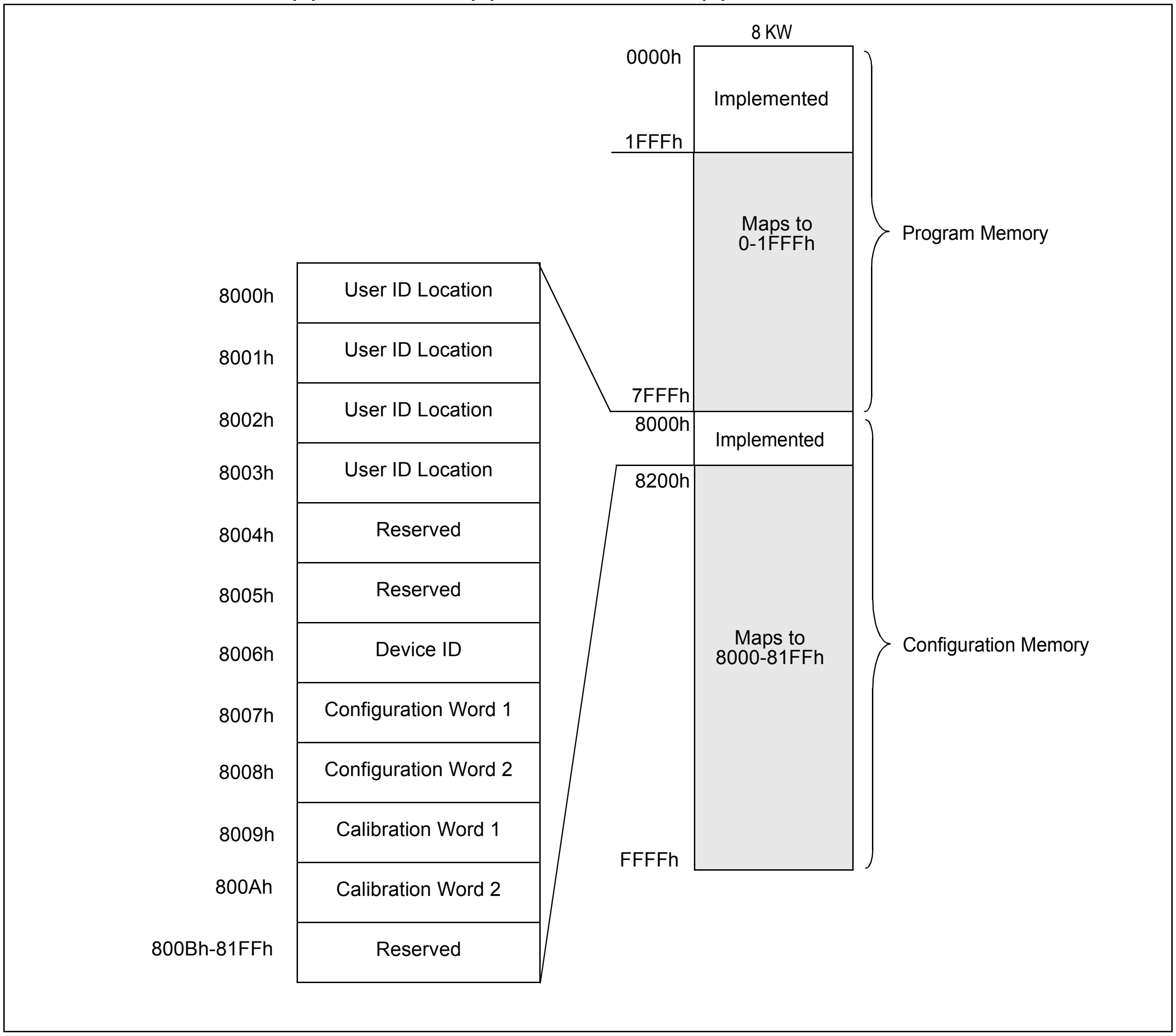
FIGURE 3-3: PIC16(L)F1526, PIC16(L)F1516 AND PIC16(L)F1517 PROGRAM MEMORY MAPPING



 Advance Information

3.1 User ID Location

A user may store identification information (user ID) in four designated locations. The user ID locations are mapped to 8000h-8003h. Each location is 14 bits in length. Code protection has no effect on these memory locations. Each location may be read with code protection enabled or disabled.

Note:	MPLAB® IDE only displays the 7 Least Significant bits (LSb) of each user ID location, the upper bits are not read. It is recommended that only the 7 LSbs be used if MPLAB IDE is the primary tool used to read these addresses.

3.2 Device ID

The device ID word is located at 8006h. This location is read-only and cannot be erased or modified.

REGISTER 3-1: DEVICE ID: DEVICE ID REGISTER(1)

R	R	R	R	R	R
DEV<8:3>					
bit 13					bit 8

R	R	R	R	R	R	R	R
DEV<2:0>			REV<4:0>				
bit 7							bit 0

Legend:	P = Programmable bit	U = Unimplemented bit, read as ‘0’
R = Readable bit	W = Writable bit	‘0’ = Bit is cleared
-n = Value at POR	‘1’ = Bit is set	x = Bit is unknown

bit 13-5 **DEV<8:0>:** Device ID bits
These bits are used to identify the part number.

bit 4-0 **REV<4:0>:** Revision ID bits
These bits are used to identify the revision.

Note 1: This location cannot be written.

REGISTER 3-2: CONFIGURATION WORD 1

R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	U-1
FCMEN	IESO	$\overline{\text{CLKOUTEN}}$	BOREN<1:0>		—
bit 13					bit 8

R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1
$\overline{\text{CP}}$	MCLRE	$\overline{\text{PWRTE}}$	WDTE<1:0>		FOSC<2:0>		
bit 7							bit 0

Legend:		
R = Readable bit	P = Programmable bit	U = Unimplemented bit, read as '1
'0' = Bit is cleared	'1' = Bit is set	-n = Value when blank or after Bulk Erase

bit 13 **FCMEN:** Fail-Safe Clock Monitor Enable bit
1 = Fail-Safe Clock Monitor is enabled
0 = Fail-Safe Clock Monitor is disabled

bit 12 **IESO:** Internal External Switchover bit
1 = Internal/External Switchover mode is enabled
0 = Internal/External Switchover mode is disabled

bit 11 **$\overline{\text{CLKOUTEN}}$:** Clock Out Enable bit
1 = CLKOUT function is disabled. I/O or oscillator function on CLKOUT pin.
0 = CLKOUT function is enabled on CLKOUT pin

bit 10-9 **BOREN<1:0>:** Brown-out Reset Enable bits(1)
11 = BOR enabled
10 = BOR enabled during operation and disabled in Sleep
01 = BOR controlled by SBOREN bit of the PCON register
00 = BOR disabled

bit 8 **Unimplemented:** Read as '1'

bit 7 **$\overline{\text{CP}}$:** Code Protection bit(2)
1 = Program memory code protection is disabled
0 = Program memory code protection is enabled

bit 6 **MCLRE:** $\overline{\text{MCLR}}$/VPP Pin Function Select bit
If LVP bit = 1:
This bit is ignored.
If LVP bit = 0:
1 = $\overline{\text{MCLR}}$/VPP pin function is $\overline{\text{MCLR}}$; Weak pull-up enabled.
0 = $\overline{\text{MCLR}}$/VPP pin function is digital input; $\overline{\text{MCLR}}$ internally disabled; Weak pull-up under control of WPUA register.

bit 5 **$\overline{\text{PWRTE}}$:** Power-up Timer Enable bit(1)
1 = PWRT disabled
0 = PWRT enabled

bit 4-3 **WDTE<1:0>:** Watchdog Timer Enable bit
11 = WDT enabled
10 = WDT enabled while running and disabled in Sleep
01 = WDT controlled by the SWDTEN bit in the WDTCON register
00 = WDT disabled

bit 2-0 **FOSC<2:0>:** Oscillator Selection bits
111 = ECH: External Clock, High-Power mode: on CLKIN pin
110 = ECM: External Clock, Medium-Power mode: on CLKIN pin
101 = ECL: External Clock, Low-Power mode: on CLKIN pin
100 = INTOSC oscillator: I/O function on OSC1 pin
011 = EXTRC oscillator: RC function on OSC1 pin
010 = HS oscillator: High-speed crystal/resonator on OSC2 pin and OSC1 pin
001 = XT oscillator: Crystal/resonator on OSC2 pin and OSC1 pin
000 = LP oscillator: Low-power crystal on OSC2 pin and OSC1 pin

Note 1: Enabling Brown-out Reset does not automatically enable Power-up Timer.
2: The entire program memory will be erased when the code protection is turned off.

4.3 Program/Verify Commands

The PIC16(L)F151X/152X implements 10 programming commands; each six bits in length. The commands are summarized in Table 4-1.

Commands that have data associated with them are specified to have a minimum delay of TDLY between the command and the data. After this delay 16 clocks are required to either clock in or clock out the 14-bit data word. The first clock is for the Start bit and the last clock is for the Stop bit.

TABLE 4-1: COMMAND MAPPING

Command	Mapping							Data/Note
	Binary (MSb … LSb)						Hex	
Load Configuration	x	0	0	0	0	0	00h	0, data (14), 0
Load Data For Program Memory	x	0	0	0	1	0	02h	0, data (14), 0
Read Data From Program Memory	x	0	0	1	0	0	04h	0, data (14), 0
Increment Address	x	0	0	1	1	0	06h	—
Reset Address	x	1	0	1	1	0	16h	—
Begin Internally Timed Programming	x	0	1	0	0	0	08h	—
Begin Externally Timed Programming	x	1	1	0	0	0	18h	—
End Externally Timed Programming	x	0	1	0	1	0	0Ah	—
Bulk Erase Program Memory	x	0	1	0	0	1	09h	Internally Timed
Row Erase Program Memory	x	1	0	0	0	1	11h	Internally Timed

4.3.1 LOAD CONFIGURATION

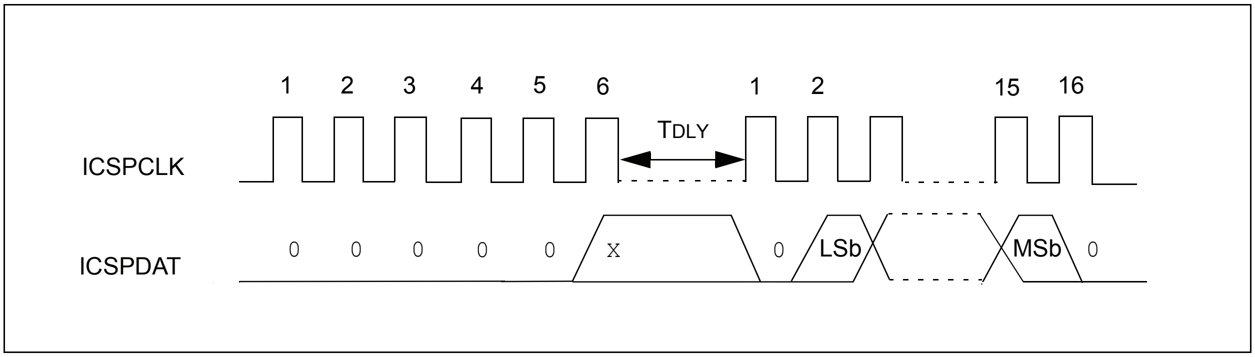
The Load Configuration command is used to access the configuration memory (User ID Locations, Configuration Words, Calibration Words). The Load Configuration command sets the address to 8000h and loads the data latches with one word of data (see Figure 4-1).

After issuing the Load Configuration command, use the Increment Address command until the proper address to be programmed is reached. The address is then programmed by issuing either the Begin Internally Timed Programming or Begin Externally Timed Programming command.

Note: Externally timed writes are not supported for Configuration and Calibration bits. Any externally timed write to the Configuration or Calibration Word will have no effect on the targeted word.

The only way to get back to the program memory (address 0) is to exit Program/Verify mode or issue the Reset Address command after the configuration memory has been accessed by the Load Configuration command.

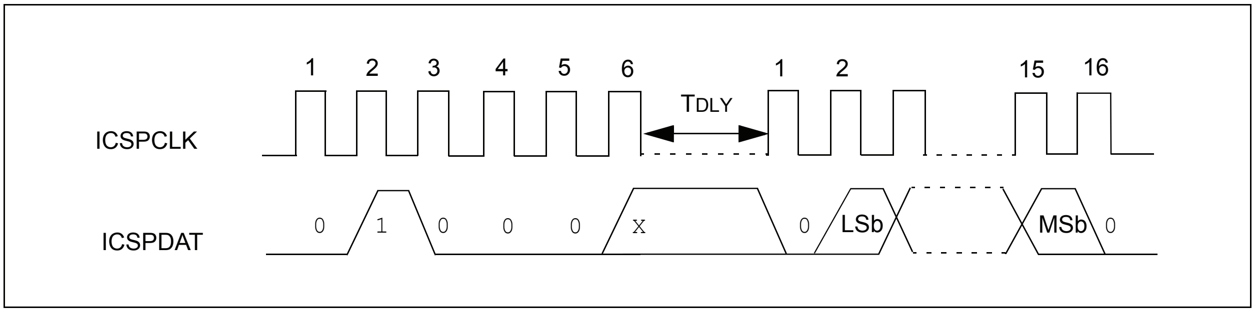
FIGURE 4-1: LOAD CONFIGURATION



4.3.2 LOAD DATA FOR PROGRAM MEMORY

The Load Data for Program Memory command is used to load one 14-bit word into the data latches. The word programs into program memory after the Begin Internally Timed Programming or Begin Externally Timed Programming command is issued (see Figure 4-2).

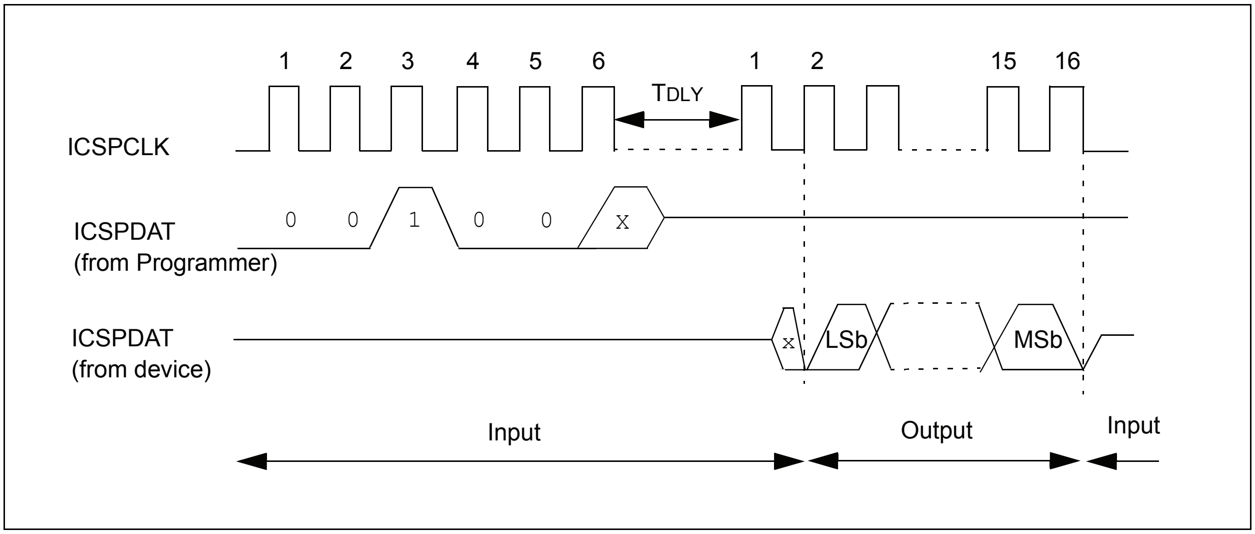
FIGURE 4-2: LOAD DATA FOR PROGRAM MEMORY



4.3.3 READ DATA FROM PROGRAM MEMORY

The Read Data from Program Memory command will transmit data bits out of the program memory map currently accessed, starting with the second rising edge of the clock input. The ICSPDAT pin will go into Output mode on the first falling clock edge, and it will revert to Input mode (high-impedance) after the 16th falling edge of the clock. If the program memory is code-protected ($\overline{CP}$), the data will be read as zeros (see Figure 4-3).

FIGURE 4-3: READ DATA FROM PROGRAM MEMORY

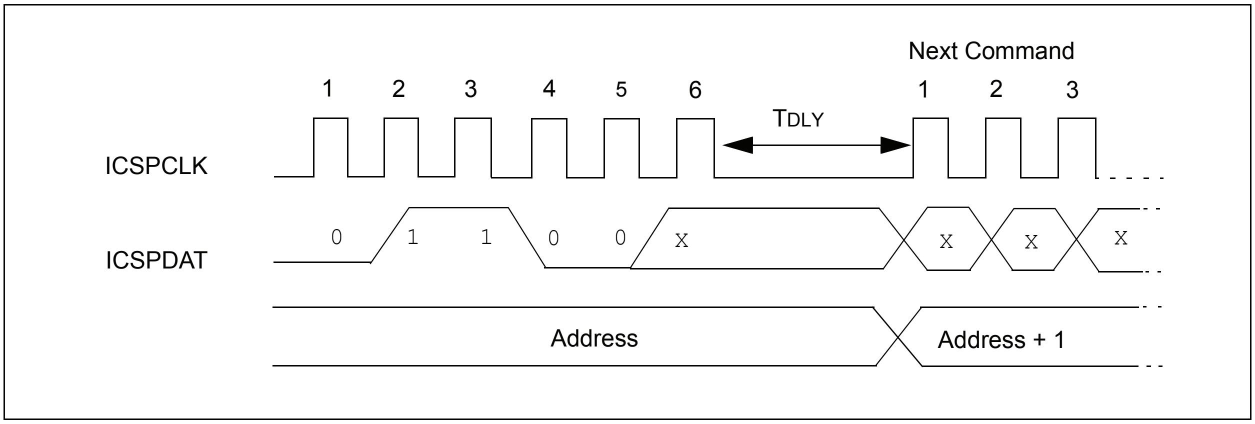


 Advance Information

4.3.4 INCREMENT ADDRESS

The address is incremented when this command is received. It is not possible to decrement the address. To reset this counter, the user must use the Reset Address command or exit Program/Verify mode and re-enter it. If the address is incremented from address 7FFFh, it will wrap-around to location 0000h. If the address is incremented from FFFFh, it will wrap-around to location 8000h.

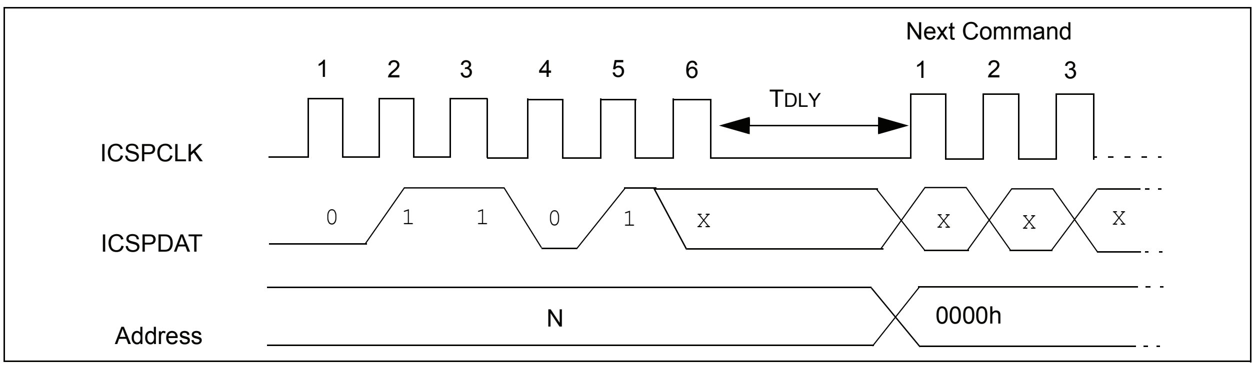
FIGURE 4-4: INCREMENT ADDRESS



4.3.5 RESET ADDRESS

The Reset Address command will reset the address to 0000h, regardless of the current value. The address is used in program memory or the configuration memory.

FIGURE 4-5: RESET ADDRESS



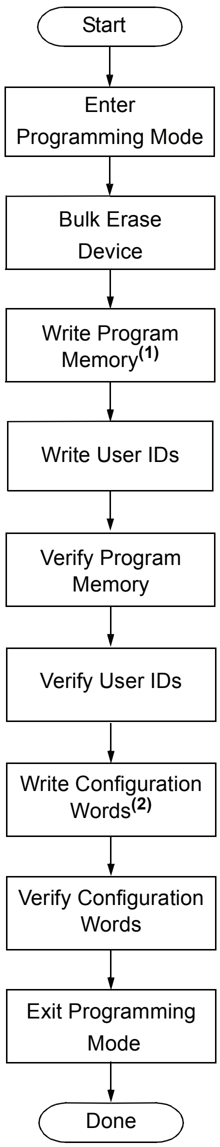
5.0 PROGRAMMING ALGORITHMS

The devices use internal latches to temporarily store the 14-bit words used for programming. Refer to Table 4-2 for specific latch information. The data latches allow the user to write the program words with a single Begin Externally Timed Programming or Begin Internally Timed Programming command. The Load Program Data or the Load Configuration command is used to load a single data latch. The data latch will hold the data until the Begin Externally Timed Programming or Begin Internally Timed Programming command is given.

The data latches are aligned with the LSbs of the address. The PC's address at the time the Begin Externally Timed Programming or Begin Internally Timed Programming command is given will determine which location(s) in memory are written. Writes cannot cross the physical boundary. For example, with the PIC16F1527, attempting to write from address 0002h-0009h will result in data being written to 0008h-000Fh.

If more than the maximum number of data latches are written without a Begin Externally Timed Programming or Begin Internally Timed Programming command, the data in the data latches will be overwritten. The following figures show the recommended flowcharts for programming.

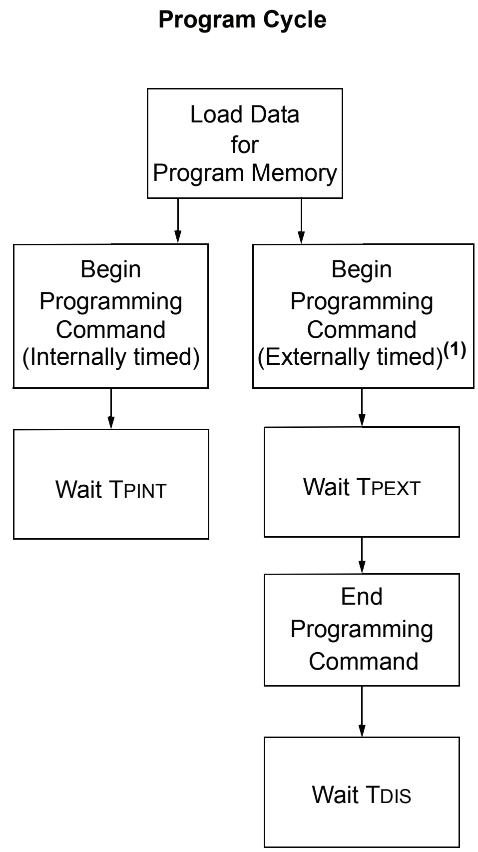
FIGURE 5-1: DEVICE PROGRAM/VERIFY FLOWCHART



Note 1: See Figure 5-2.
2: See Figure 5-5.

 Advance Information

FIGURE 5-3: ONE-WORD PROGRAM CYCLE



Note 1: Externally timed writes are not supported for Configuration and Calibration bits.

 Advance Information

EXAMPLE 7-1: CHECKSUM COMPUTED WITH PROGRAM CODE PROTECTION DISABLED PIC16F1527, BLANK DEVICE

PIC16F1527	Sum of Memory addresses 0000h-3FFFh(1)	C000h
	Configuration Word 1(2)	3FFFh
	Configuration Word 1 mask(3)	3EFFh
	Configuration Word 2(2)	3FFFh
	Configuration Word 2 mask(3)	3E13h
	Checksum	= C000h + (3FFFh and 3EFFh) + (3FFFh and 3E13h)
		= C000h + 3EFFh + 3E13h
		= 3D12h

Note 1: Sum of memory addresses = (Total number of program memory address locations) x (3FFFh) = C000h, truncated to 16 bits.

2: Configuration Word 1 and 2 = all bits are '1'; thus, code-protect is disabled.

3: Configuration Word 1 and 2 Mask = all bits are set to '1', except for unimplemented bits that are '0'.

EXAMPLE 7-2: CHECKSUM COMPUTED WITH PROGRAM CODE PROTECTION DISABLED PIC16LF1527, 00AAh AT FIRST AND LAST ADDRESS

PIC16LF1527	Sum of Memory addresses 0000h-3FFFh(1)	4156h
	Configuration Word 1(2)	3FFFh
	Configuration Word 1 mask(3)	3EFFh
	Configuration Word 2(2)	3FFFh
	Configuration Word 2 mask(4)	3E03h
	Checksum	= 4156h + (3FFFh and 3EFFh) + (3FFFh and 3E03h)
		= 4156h + 3EFFh + 3E03h
		= BE58h

Note 1: Total number of Program memory address locations: 3FFFh + 1 = 4000h. Then, 4000h - 2 = 3FFEh. Thus, [(3FFEh x 3FFFh) + (2 x 00AAh)] = 4156h, truncated to 16 bits.

2: Configuration Word 1 and 2 = all bits are '1'; thus, code-protect is disabled.

3: Configuration Word 1 Mask = all Configuration Word bits are set to '1', except for unimplemented bits that are '0'.

4: On the PIC16LF1527 device, the $\overline{\text{VCAPEN}}$ bit is not implemented in Configuration Word 2; Thus, all unimplemented bits are '0'.

8.0 ELECTRICAL SPECIFICATIONS

Refer to device specific data sheet for absolute maximum ratings.

TABLE 8-1: AC/DC CHARACTERISTICS TIMING REQUIREMENTS FOR PROGRAM/VERIFY MODE

AC/DC CHARACTERISTICS			**Standard Operating Conditions** Production tested at 25°C				
Sym.	**Characteristics**		**Min.**	**Typ.**	**Max.**	**Units**	**Conditions/Comments**
	Supply Voltages and Currents						
VDD	Supply Voltage (VDDMIN, VDDMAX)	PIC16F151X PIC16F152X	2.3	—	5.5	V	
		PIC16LF151X PIC16LF152X	1.8	—	3.6	V	
VPEW	Read/Write and Row Erase operations		VDDMIN	—	VDDMAX	V	
VPBE	Bulk Erase operations		2.7	—	VDDMAX	V	
IDDI	Current on VDD, Idle		—	—	1.0	mA	
IDDP	Current on VDD, Programming		—	—	3.0	mA	
	VPP						
IPP	Current on MCLR/VPP		—	—	600	μA	
VIHH	High voltage on MCLR/VPP for Program/Verify mode entry		8.0	—	9.0	V	
TVHHR	MCLR rise time (VIL to VIHH) for Program/Verify mode entry		—	—	1.0	μs	
	I/O pins						
VIH	(ICSPCLK, ICSPDAT, MCLR/VPP) input high level		0.8 VDD	—	—	V	
VIL	(ICSPCLK, ICSPDAT, MCLR/VPP) input low level		—	—	0.2 VDD	V	
VOH	ICSPDAT output high level		VDD-0.7 VDD-0.7 VDD-0.7	—	—	V	IOH = 3.5 mA, VDD = 5V IOH = 3 mA, VDD = 3.3V IOH = 2 mA, VDD = 1.8V
VOL	ICSPDAT output low level		—	—	VSS+0.6 VSS+0.6 VSS+0.6	V	IOH = 8 mA, VDD = 5V IOH = 6 mA, VDD = 3.3V IOH = 3 mA, VDD = 1.8V
	Programming Mode Entry and Exit						
TENTS	Programing mode entry setup time: ICSPCLK, ICSPDAT setup time before VDD or MCLR↑		100	—	—	ns	
TENTH	Programing mode entry hold time: ICSPCLK, ICSPDAT hold time after VDD or MCLR↑		250	—	—	μs	
	Serial Program/Verify						
TCKL	Clock Low Pulse Width		100	—	—	ns	
TCKH	Clock High Pulse Width		100	—	—	ns	
TDS	Data in setup time before clock↓		100	—	—	ns	
TDH	Data in hold time after clock↓		100	—	—	ns	
TCO	Clock↑ to data out valid (during a Read Data command)		0	—	80	ns	
TLZD	Clock↓ to data low-impedance (during a Read Data command)		0	—	80	ns	
THZD	Clock↓ to data high-impedance (during a Read Data command)		0	—	80	ns	
TDLY	Data input not driven to next clock input (delay required between command/data or command/ command)		1.0	—	—	μs	
TERAB	Bulk Erase cycle time		—	—	5	ms	
TERAR	Row Erase cycle time		—	—	2.5	ms	

Note 1: Externally timed writes are not supported for Configuration and Calibration bits.

TABLE 8-1: AC/DC CHARACTERISTICS TIMING REQUIREMENTS FOR PROGRAM/VERIFY

AC/DC CHARACTERISTICS		Standard Operating Conditions Production tested at 25°C				
Sym.	**Characteristics**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions/Comments**
TPINT	Internally timed programming operation time	— —	— —	2.5 5	ms ms	Program memory Configuration Words
TPEXT	Externally timed programming pulse	1.0	—	2.1	ms	**Note 1**
TDIS	Time delay from program to compare (HV discharge time)	300	—	—	µs	
TEXIT	Time delay when exiting Program/Verify mode	1	—	—	µs	

Note 1: Externally timed writes are not supported for Configuration and Calibration bits.

8.1 AC Timing Diagrams

FIGURE 8-1: PROGRAMMING MODE ENTRY – VDD FIRST

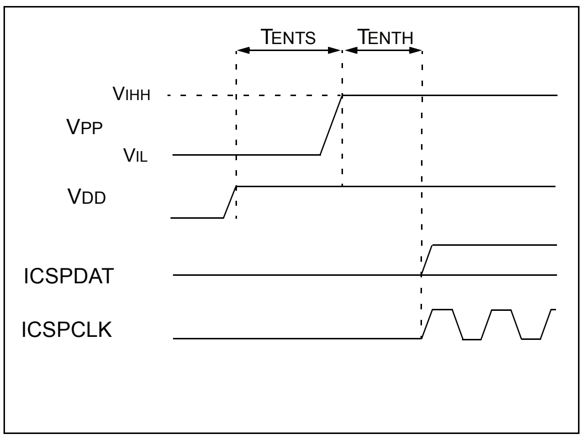


FIGURE 8-2: PROGRAMMING MODE ENTRY – VPP FIRST

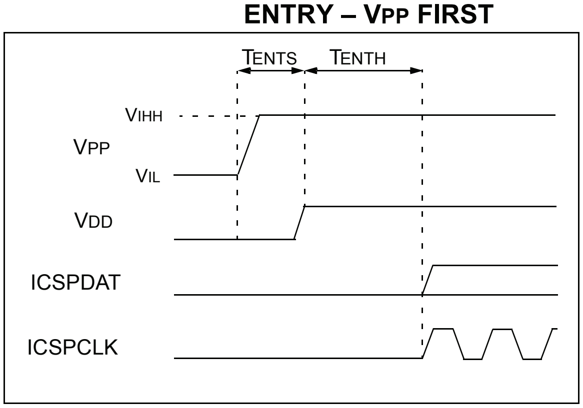


FIGURE 8-3: PROGRAMMING MODE EXIT – VPP LAST

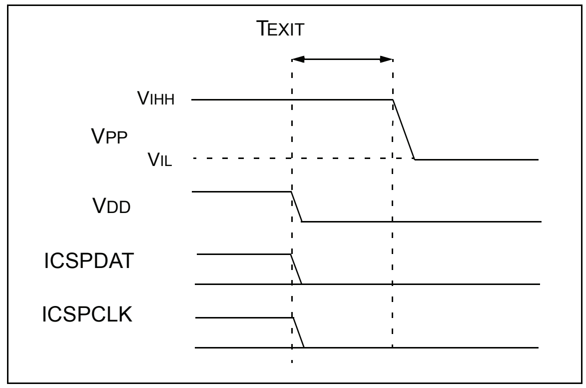


FIGURE 8-4: PROGRAMMING MODE EXIT – VDD LAST

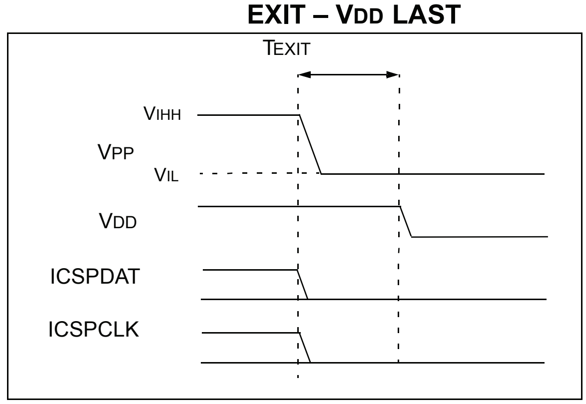


FIGURE 8-8: LVP ENTRY (POWERED)

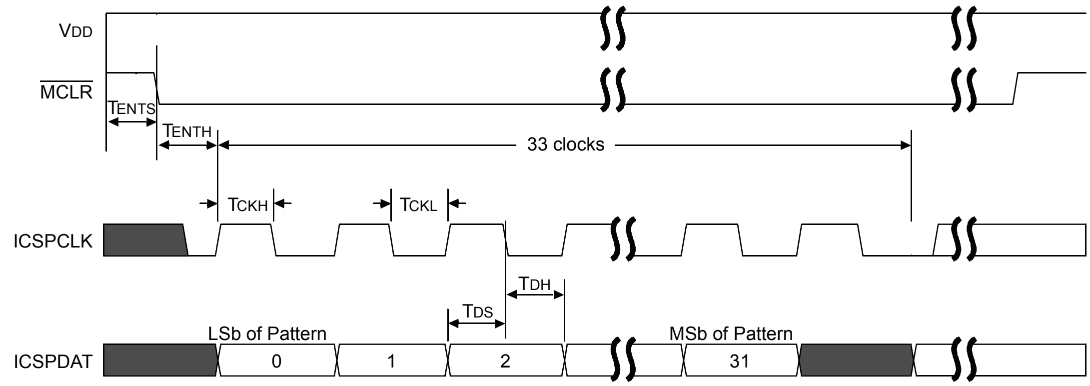
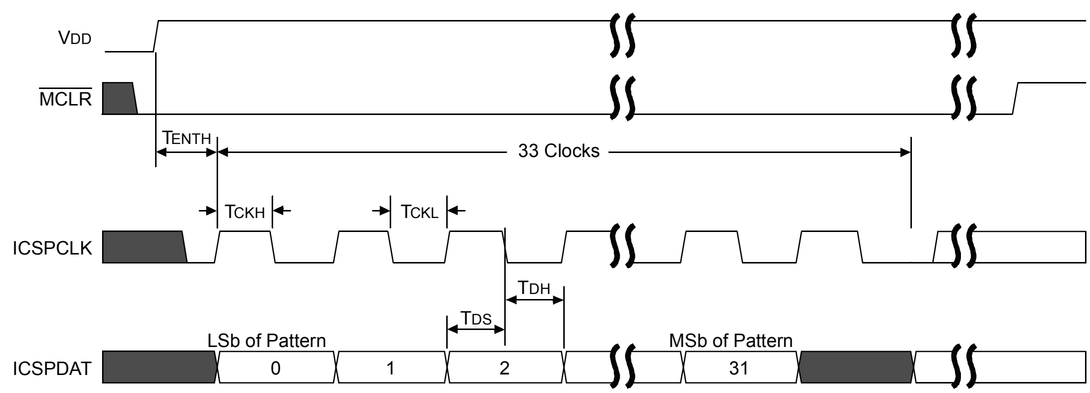


FIGURE 8-9: LVP ENTRY (POWERING UP)



Note 1: Sequence matching can start with no edge on $\overline{MCLR}$ first.

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
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